

30V N-Channel Enhancement Mode MOSFET

Description

The AP60N03DF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 30V$ $I_D = 60A$

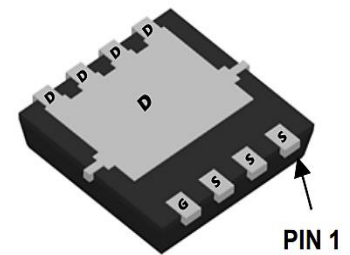
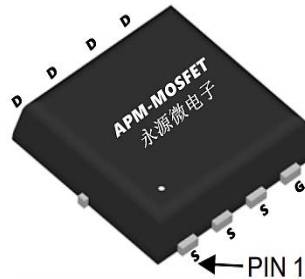
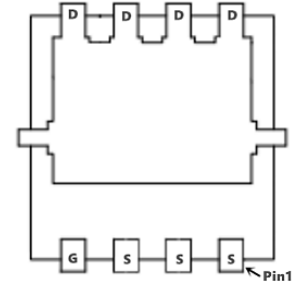
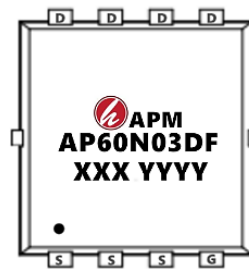
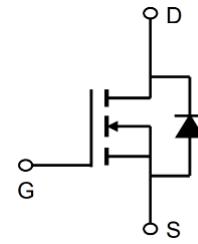
$R_{DS(ON)} < 8.5m\Omega$ @ $V_{GS}=10V$ (Type: 6.0m Ω)

Application

VBUS

Wireless impact

Mobile phone fast charging



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP60N03DF	PDFN3*3-8L	AP60N03DF XXX YYYY	5000

Absolute Maximum Ratings ($T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, V_{GS} @ 10V ¹	60	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, V_{GS} @ 10V ¹	29	A
I_{DM}	Pulsed Drain Current ²	92	A
E_{AS}	Single Pulse Avalanche Energy ³	57.8	mJ
I_{AS}	Avalanche Current	34	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation ⁴	29	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	62.5	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	4.32	$^{\circ}C/W$

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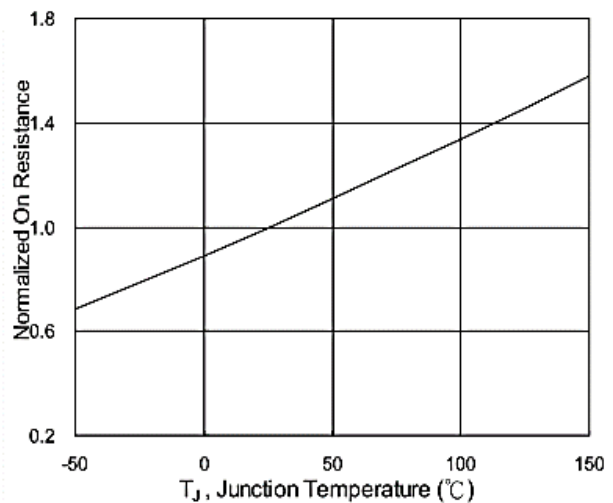
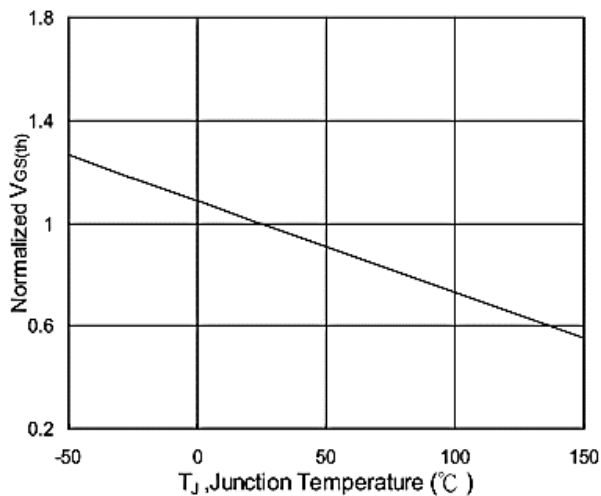
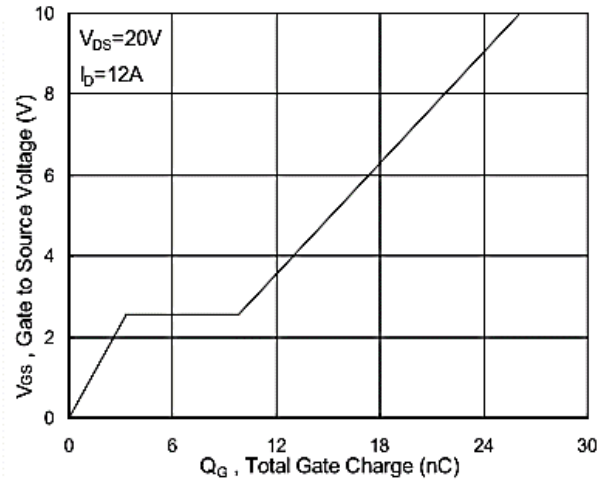
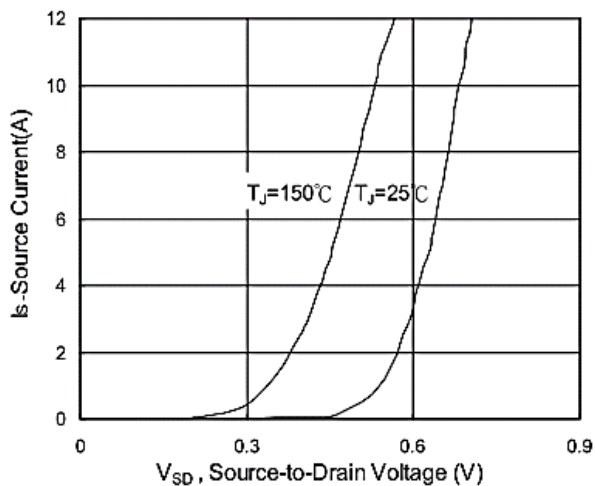
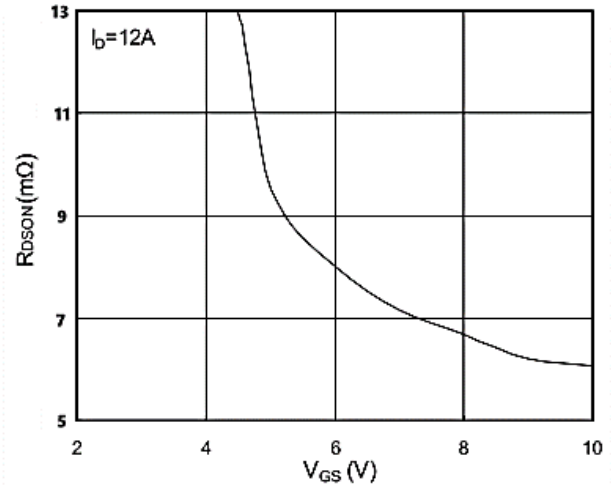
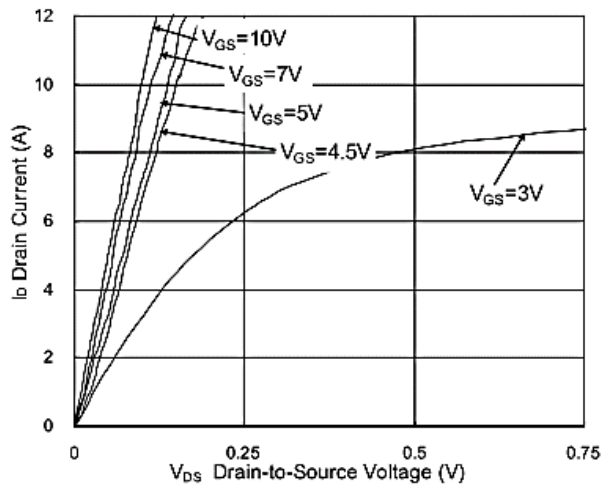
Electrical Characteristics (T_c=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	33	---	V
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =12A	---	6.0	8.5	mΩ
		V _{GS} =4.5V, I _D =10A	---	8.0	13	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.6	2.5	V
ΔVGS(th)	V _{GS(th)} Temperature Coefficient		---	-5.8	---	mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =24V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =24V, V _{GS} =0V, T _J =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
gfs	Forward Transconductance	V _{DS} =5V, I _D =15A	---	9.8	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	1.7	---	Ω
Q _g	Total Gate Charge (4.5V)	V _{DS} =20V, V _{GS} =4.5V, I _D =12A	---	12.8	---	nC
Q _{gs}	Gate-Source Charge		---	3.3	---	
Q _{gd}	Gate-Drain Charge		---	6.5	---	
Td(on)	Turn-On Delay Time	V _{DD} =12V, V _{GS} =10V, R _G =3.3Ω, I _D =5A	---	4.5	---	ns
T _r	Rise Time		---	10.8	---	
Td(off)	Turn-Off Delay Time		---	25.5	---	
T _f	Fall Time		---	9.6	---	
Ciss	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	---	1317	---	pF
Coss	Output Capacitance		---	163	---	
Crss	Reverse Transfer Capacitance		---	131	---	
IS	Continuous Source Current ^{1,6}	V _G =V _D =0V, Force Current	---	---	46	A
ISM	Pulsed Source Current ^{2,6}		---	---	92	A
VSD	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V

Note :

- 1、The data tested by surface mounted on a 1 inch2 FR-4 board with 20Z copper.
- 2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=34A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics



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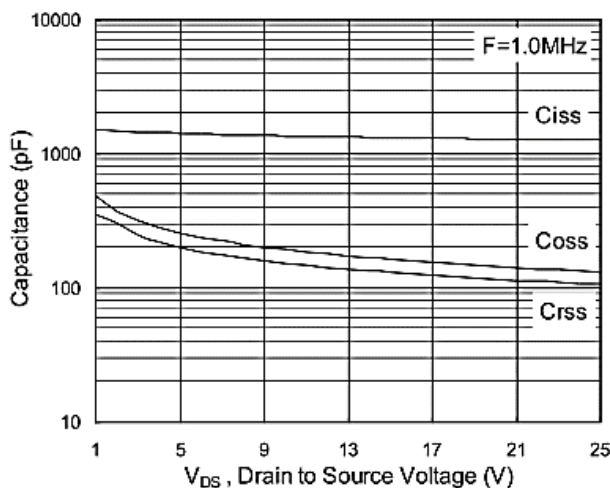


Fig.7 Capacitance

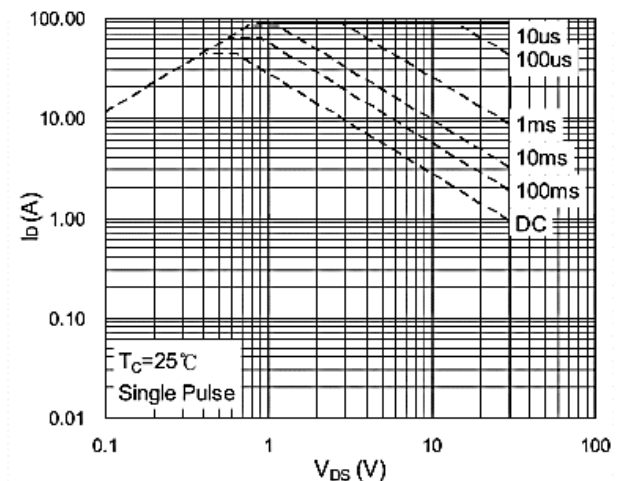


Fig.8 Safe Operating Area

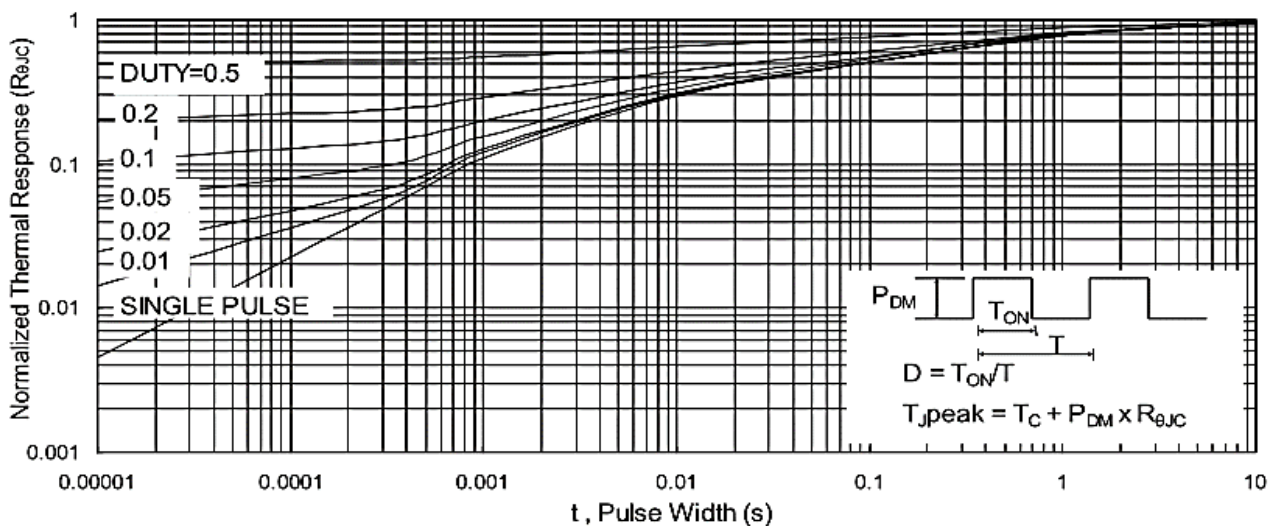


Fig.9 Normalized Maximum Transient Thermal Impedance

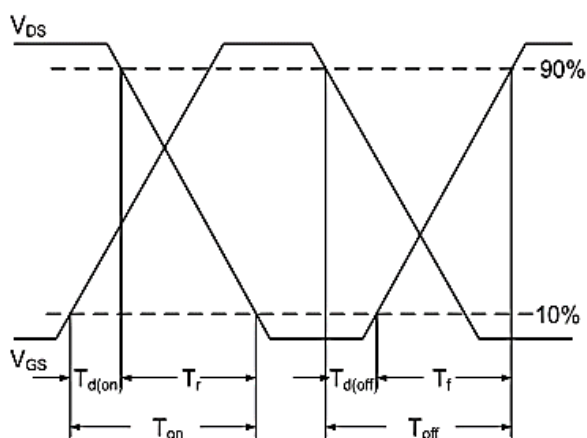


Fig.10 Switching Time Waveform

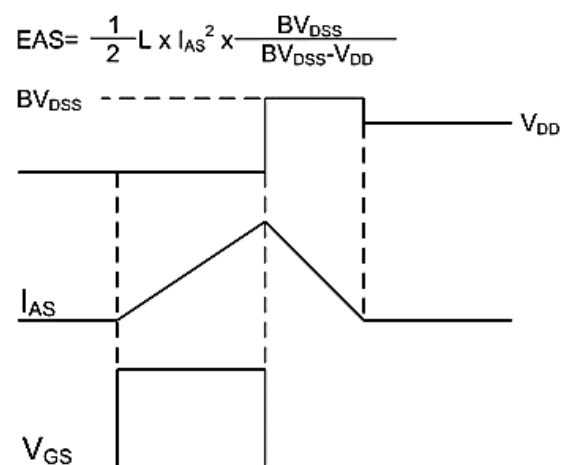
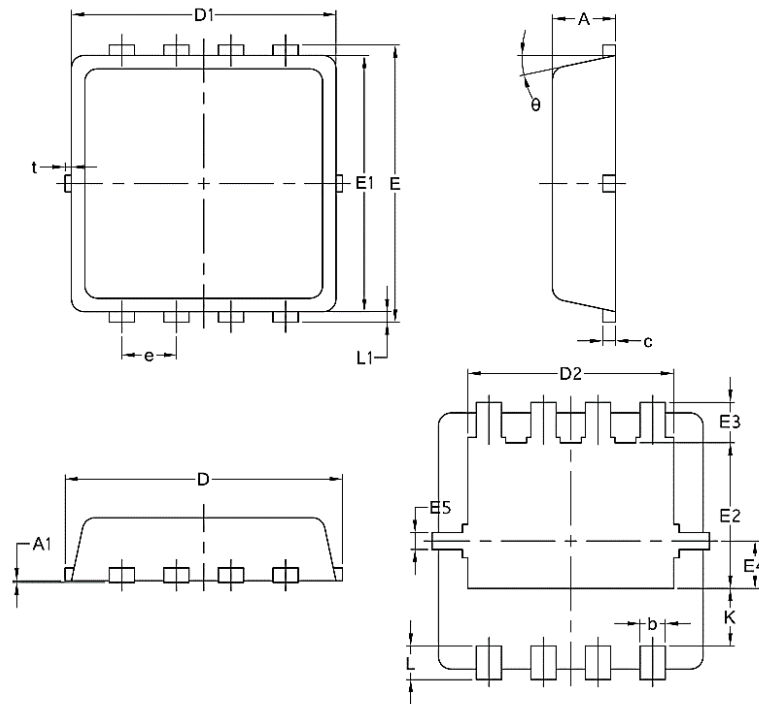


Fig.11 Unclamped Inductive Switching Waveform

Package Mechanical Data-DFN3*3-8L-JQ Single



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14

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Edition	Date	Change
Rve1.0	2019/4/10	Initial release
Rve1.1	2022/1/10	Reduce internal RDS

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